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FDW256P

30V P-Channel PowerTrench MOSFET

General Description

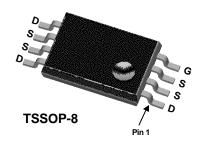
This PChannel MOSFET is a rugged gate version of Fairchild Semiconductor's advanced PowerTrench process. It has been optimized for power management applications requiring a wide range of gave drive voltage ratings (4.5V-25V).

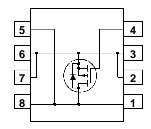
Applications

- · Battery protection
- DC/DC conversion
- · Power management
- Load switch

Features

- -8 A, -30 V $R_{DS(ON)} = 13.5 \text{ m}\Omega$ @ $V_{GS} = -10 \text{ V}$ $R_{DS(ON)} = 20 \text{ m}\Omega$ @ $V_{GS} = -4.5 \text{ V}$
- Extended V_{GSS} range (±25V) for battery applications
- High performance trench technology for extremely low R_{DS(ON)}
- · Low profile TSSOP-8 package





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		-30	V
V _{GSS}	Gate-Source Voltage		± 25	V
l _D	Drain Current - Continuous	(Note 1)	-8	А
	- Pulsed		– 50	
P _D	Power Dissipation	(Note 1a)	1.3	W
		(Note 1b)	0.6	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	96	°C/W
		(Note 1b)	208	

Package Marking and Ordering Information

		<u> </u>	J		
	Device Marking	Device	Reel Size	Tape width	Quantity
_	256P	FDW256P	13"	16mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
	 acteristics					
BV _{DSS}	Drain–Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-30			V
ΔBV DSS	Breakdown Voltage Temperature		- 50			-
<u>ΔΒV D33</u> ΔΤ _J	Coefficient	$I_D = -250 \mu\text{A}$, Referenced to 25°C		-23		mV/°C
l _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μΑ
I _{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = 25 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)			•		
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-1	-1.7	-3	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$, Referenced to 25°C		5		mV/°C
R _{DS(on)}	Static Drain-Source	$V_{GS} = -10 \text{ V}, I_D = -8.0 \text{ A}$		11	13.5	mΩ
	On–Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -6.5 \text{ A}$		16	20	
		V_{GS} =-10 V, I_D =-8.0A, T_J =125°C		15	19	
$I_{D(on)}$	On–State Drain Current	$V_{GS} = -10 \text{ V}, V_{DS} = -5 \text{ V}$	- 50			Α
g FS	Forward Transconductance	$V_{DS} = -5 \text{ V}, \qquad I_{D} = -8.0 \text{ A}$		30		S
Dynamic	: Characteristics					
Ciss	Input Capacitance	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V},$		2267		pF
Coss	Output Capacitance	f = 1.0 MHz		599		pF
C _{rss}	Reverse Transfer Capacitance			315		pF
Switchin	g Characteristics (Note 2)			•		•
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -15 \text{ V}, I_D = -1 \text{ A},$		15	27	ns
t _r	Turn-On Rise Time	$V_{GS} = -10 \text{ V}, R_{GEN} = 6 \Omega$		11	35	ns
t _{d(off)}	Turn-Off Delay Time			78	125	ns
t _f	Turn-Off Fall Time			45	72	ns
Qg	Total Gate Charge	$V_{DS} = -15 \text{ V}, I_{D} = -8.0 \text{ A},$		28	38	nC
Q _{gs}	Gate-Source Charge	V _{GS} = -5.0V		7		nC
Q _{gd}	Gate-Drain Charge	1		12		nC
Drain-Se	ource Diode Characteristics	and Maximum Ratings	1	1	ı	
ls	Maximum Continuous Drain–Source				-1.2	Α
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = -1.2 \text{ A} \text{(Note 2)}$		-0.7	-1.2	V

Notes

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^{1.} R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{BJC} is guaranteed by design while R_{BCA} is determined by the user's board design.

a) $\rm R_{\rm \theta JA}$ is 96 °C/W (steady state) when mounted on a 1 inch² copper pad on FR-4.

b) $\rm R_{\theta JA}$ is 208 °C/W (steady state) when mounted on a minimum copper pad on FR-4.

^{2.} Pulse Test: Pulse Width < $300\mu s$, Duty Cycle < 2.0%

Typical Characteristics

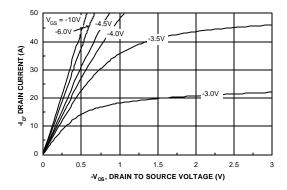


Figure 1. On-Region Characteristics.

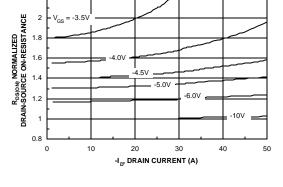


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

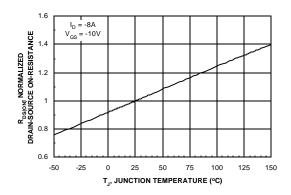


Figure 3. On-Resistance Variation with Temperature.

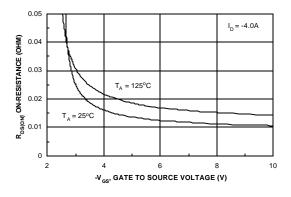


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

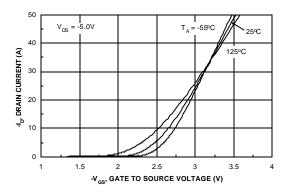


Figure 5. Transfer Characteristics.

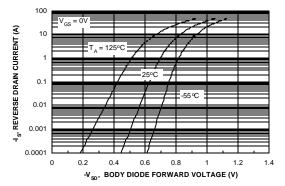
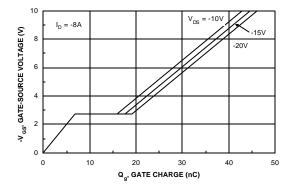


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

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Typical Characteristics



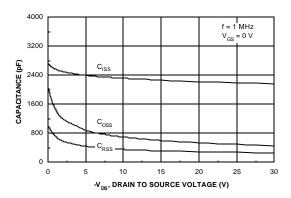
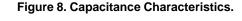
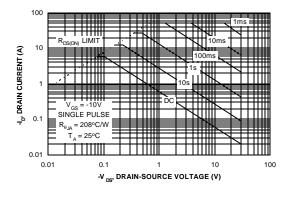


Figure 7. Gate Charge Characteristics.





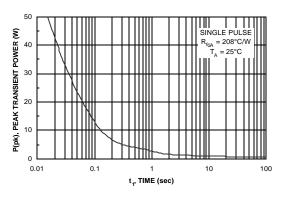


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

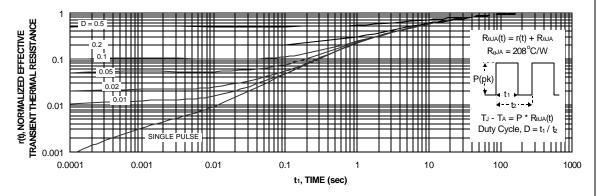


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

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